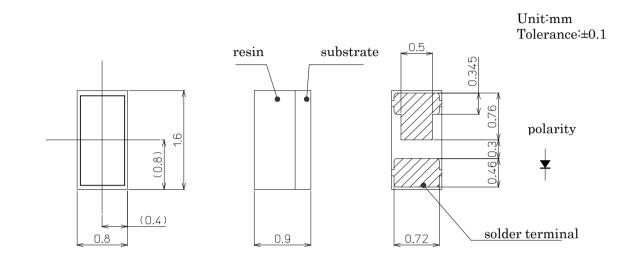
		of Application specifications are applied to	the chip ty	vpe LED la	amp , mod	lel CL-824	-MU1W1-T
	2. Part c	ode					
		C L -	824	<u>1</u> - <u>M</u>	$\underline{U1}$ W	<u>′1</u> - <u>T</u> ∣	
		Series 824 : White LED for genera	al lighting.				
		Special specifications — M : General Color Rende		с Тур. 85 Т	Гуре.		
		Watt Class U1 : Under 1 watt packag	ge.				
		Lighting color		Temperat	cure 4000	(K)	
		Shipping mode					
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3. Outline drawing



4. Performance

(1) Absolute Maximum Rating	g			
	Parameter	Symbol	Rating Value	Unit	
	Power Dissipation	Pd	108	mW	
	Forward Current	$I_{\rm F}$	30	mA	
	Forward Pulse Current	$I_{\rm FP}$	100	mA	*1
	Reverse Voltage	$V_{\rm R}$	5	V	
	Operating Temperature	T _{OP}	$-30 \sim +85$	С	
	Storage Temperature	T_{ST}	-40 ~ +100	С]
	Junction Temperature	Tj _{Max}	120	С	*2

*1Forward Current : Duty≤1/10 , Pulse Width≤0.1msec

*2 D.C. Current : Tj = Tc + Rj·s x Pd Pulse Current : Tj = Tc + Rj·s x Pw(Power Dissipation / one-Pulse) x duty Tc:Temperature of anode solder terminal

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(2) Electro-optical	Characte	ristics				(Tc=25°C
Parameter	Symbol	Condition	MIN	TYP	MAX	Unit
Forward Voltage	$V_{\rm F}$	I _F =20mA	2.8	3.2	3.5	V
Reverse Current	I _R	$V_R=5V$	-	-	100	μA
Thermal resistance	R_{j-s}	Junction-solder	-	175	-	C/W
Luminous Intensity *1	I_v	I _F =20mA	1240	1730	-	mcd
Luminous Flux	$\phi_{\rm V}$	I _F =20mA	-	(4.8)	-	lm
General Color Rendering Index	Ra	I _F =20mA	80	85	-	-

*1 In accordance with NIST standard

Ranking (Condition : I_F =20mA , T_c =25C)

Parameter	Symbol	Rank	MIN	MAX	Unit
		Q	2.8	3.0	
Forward Voltage	$V_{\rm F}$	R	3.0	3.2	V
		S	3.2	3.5	
		В	1240	1405	
Luminous Intensity	I_v	С	1405	1900	mcd
		D	1900	2569	

Chromaticity coordinates

(Condition : $I_F=20$ mA , Tc=25C)

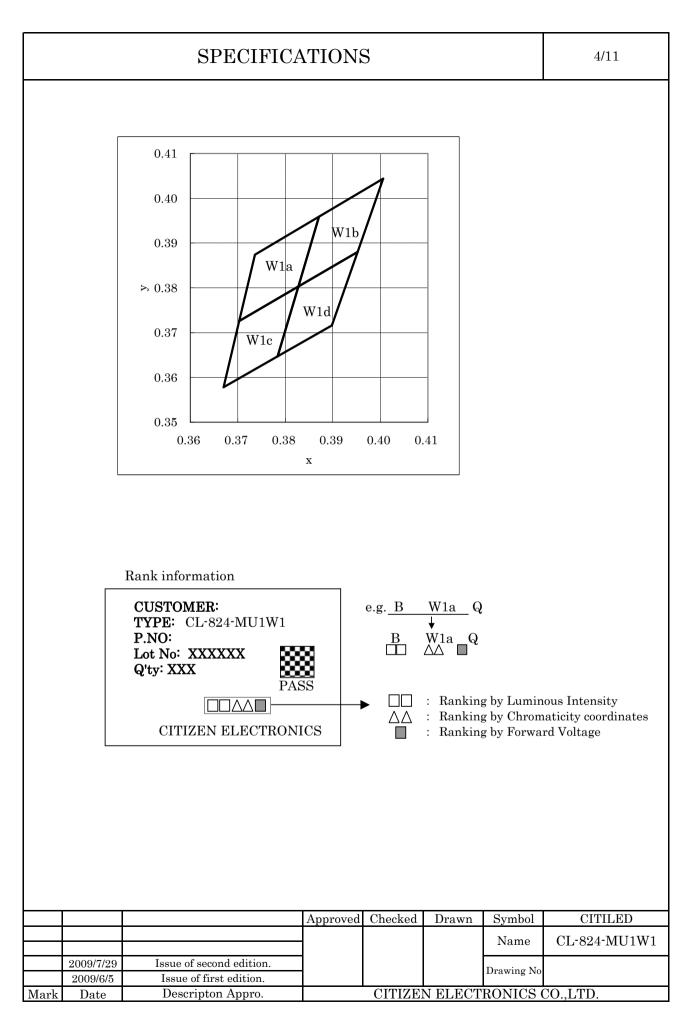
Color Rank	Х	У	Color Rank	Х	У
	0.3871	0.3959		0.4006	0.4044
W1o	0.3736	0.3874	W1b	0.3871	0.3959
W1a	0.3703	0.3726	VV ID	0.3828	0.3803
	0.3828	0.3803		0.3952	0.3880

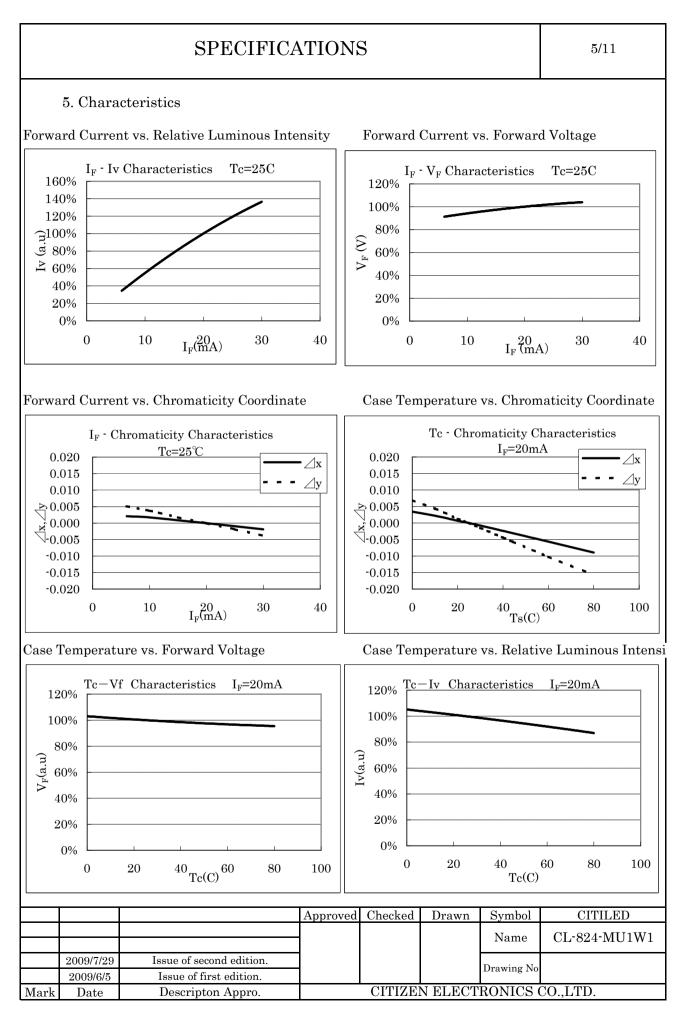
Color Rank	X	У	Color Rank	Х	У
	0.3828	0.3803		0.3952	0.3880
W1 o	0.3703	0.3726	W1d	0.3828	0.3803
W1c	0.3670	0.3578	W IU	0.3784	0.3647
	0.3784	0.3647		0.3898	0.3716

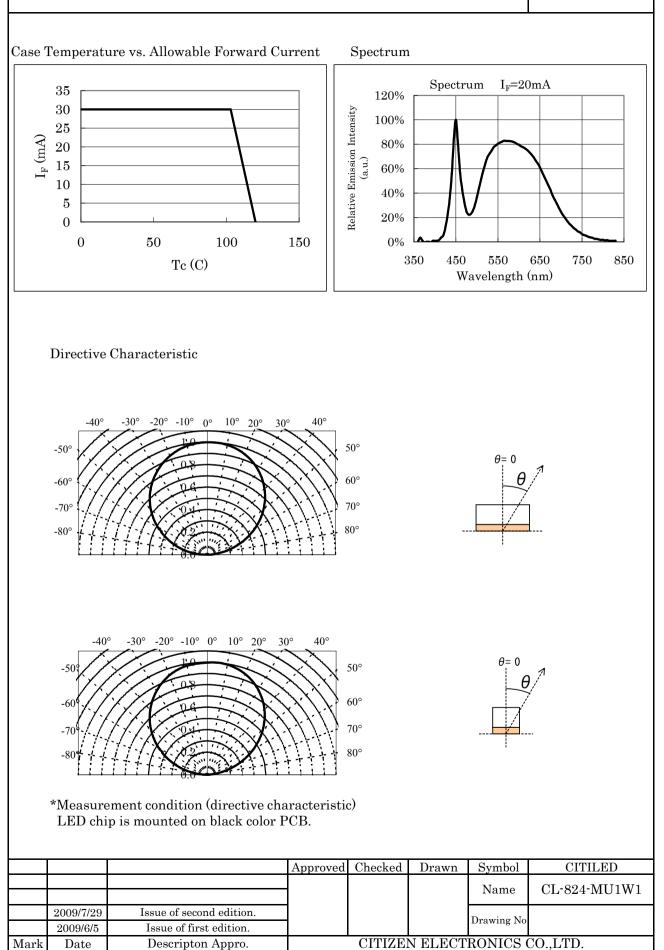
Note 1) The tolerance of measurement at our tester is $V_F\pm 3\%$, $\phi v\pm 10\%$, Chromaticity(x,y)\pm 0.01. Note 2) For handling ,please apply CMOS LSI or equivalent any electrostatic effect.

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6. Reliability

(1)Details of the tests

Test Item	Test Condition
Life Test in Continuous Operation	25±3C, $\rm I_F{=}20~mA$, $\rm 1000_{+24/{-}12}hours$
Low Temperature Storage Test	$-40_{+3/-5}$ C , $1000_{+24/-12}$ hours
High Temperature Storage Test	$100_{+5/\cdot 3}C$, $1000_{+24/\cdot 12}hours$
Moisture-proof Test	$60 \pm 2^{\circ}$ C, $90 \pm 5\%$ RH for $1000_{+24/\cdot 12}$ hours
Thermal Shock Test	-40C , 30 minutes and 100C , 30 minutes, 100cycle
Solder Heat Resistance Test	Recommended temperature profile (reflow soldering) × 2, (2nd test must be started after the samples

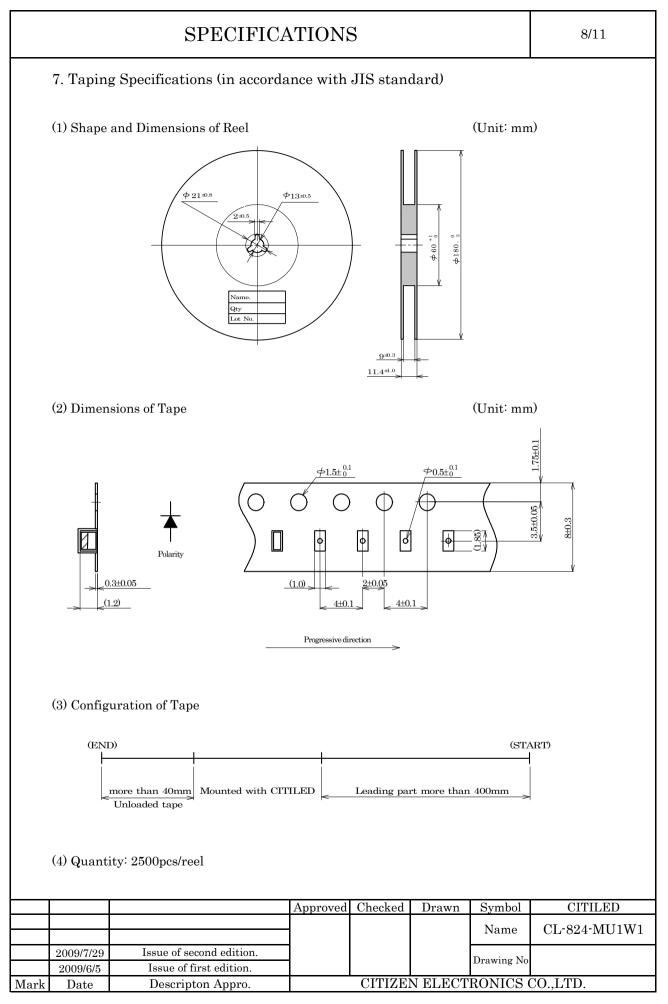
(2)Judgment Criteri	a of Failure for Reliability Te	st $(Ta=25C)$
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(=) o wagino no o									
Measuring Item	Symbol	Measuring Condition	Judgement Criteria for Failure						
Forward Voltage	$V_{\rm F}$	I _F =20mA	>U×1.2						
Reverse Current	I_R	$V_R=5V$	>U×2						
Luminous Intensity	I_V	I _F =20mA	<s×0.7< td=""></s×0.7<>						

U defines the upper limit of the specified characteristics.S defines the initial value.

Note: Measurement shall be taken between 2 hours and 24 hours, and the test pieces should be returned to the normal ambient conditions after the completion of each test.

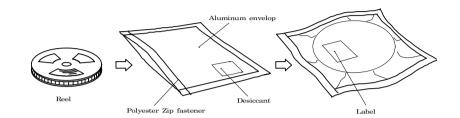
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8. Packing Specifications

8-1. Moisture-proof Packing

To prevent moisture absorption during transportation and storage, reels are packed in aluminum envelopes which contain a desiccant with a humidity indicator.



8-2. Storage

To prevent moisture absorption, it is strongly recommended that reels (in bulk or taped) should be stored in the dry box (or the desiccator) with a desiccant as the appropriate storage place. If not, the following is recommended.

Temperature:	5~30C
Humidity:	60%RH max

The devices should be mounted as soon as possible after unpacking. If you store the unpacked reels, please store them in the dry box or seal them into the envelop again.

MSL 1 (IPC/JEDEC J-STD-020C)

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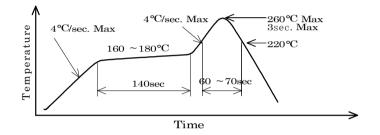
Ref.CE-P484 08/09

9. Precautions

9-1. Soldering

(1) Lead free soldering

- Following soldering paste is recommended Melting temperature: 216 ~ 220°C. Composition: Sn 3.5Ag 0.75Cu
- 2) The temperature profile at the top surface of the parts is recommended as shown below.
- 3) It is requested that products should be handled after their temperature has dropped down to the normal room temperature



9-2. Washing

(1) When washing after soldering is needed, following conditions are requested.

a) Washing solvent: Pure Water

b) Temperature, time: 50C or less \times 30 seconds max. or 30C or less \times 3 minutes max.

c) Ultrasonic washing: 300W or less

9-3. Other directions

(1) It is requested to avoid any stress added to the resin portion while it is heated.

(2) It is requested to avoid any friction by sharp metal nail etc. to the resin portion.

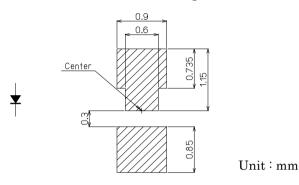
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10. Designing precautions

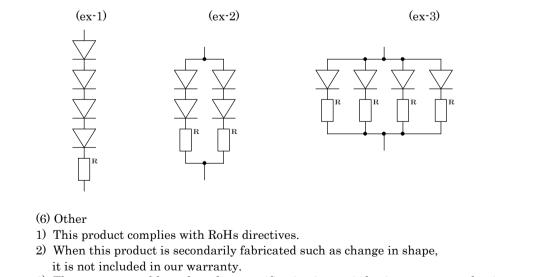
- (1) The current limiting resistor should be placed in the circuit so that is driven within its rating. Also avoid reverse voltage (over-current) applied instantaneously when ON or OFF.
- (2) When pulse driving current is applied, average current consumption should be within the rating. Also avoid reverse voltage applied when put off.
- (3) Recommended soldering pattern

<For reflow soldering>



The above dimensions are not the one which guarantee the performance of mountability. The use of the above pattern is recommended to use after deep study at your site.

- (4) When assembling the circuit board into the finished products, care must be taken to avoid the component parts from touching other parts.
- (5) When using multiple LEDs, it is required to connect a current limiting resistor on each path which the current flows to the LEDs.



3) The agreement of formal product specification is requied prior to mass production.

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